

### **In The Specification**

Please replace the paragraph beginning on page 6, line 19 with the following annotated paragraph, wherein the amended material is underlined:

FIG. 2D is a top view of the interconnection of FIG. 2C. The conductive via plugs 251 and 252 are arranged along the upper metal line 250 and the lower metal line 230. The upper metal line 250, having a first end 221 and a second end (not shown), is connected to the lower metal line by both the conductive via plugs 251 and 252 near the first end 221, wherein the via plug 251 is closer to the first end 221 end point of the metal line 230 than the via plug 252. The direction extending from the first end 221 to the second end is parallel to the substrate surface 201.

Please replace the paragraph beginning on page 8, line 4 with the following annotated paragraph, wherein the amended material is underlined:

A passivation layer or a dielectric layer 360 is then formed, filling the via hole closest to the end point of metal layer 330 as a non-conductive via plug 361 and covering the metal layer 350 and the dielectric layer 340. Further referring to Figs. 3A and 3B, the metal layer 350 is preferably a lower metal line having a first end 321 and a second end (not shown), wherein the direction extending from the first end 321 to the second end is parallel to the substrate surface 301. The upper metal layer 350 is also preferably an upper metal line. As shown in FIG. 3A, via plugs 352 and 361 are preferably arranged along the lower metal line 330. The via plug 361 is closer to the first end 321 than the via plug 352. The upper metal

line 350 connects the lower metal line 330 trough via plug 361 without connecting to the via plug 361.